

Migrating from OMAP3530 to AM37x

ARM MPU Applications

ABSTRACT

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http://processors.wiki.ti.com/index.php/OMAP35x_To_AM37x_Hardware_Migration_Guide.

The OMAP35x to AM37x Hardware Migration Guide describes device considerations to migrate a design based on the TI OMAP3530 Applications Processor to one based on the TI AM/DM37x Applications Processor. The document provides a feature set comparison and discusses the enhanced features of the AM/DM37x and differences in hardware details, ballmap, operating points, pin multiplexing, ROM code and errata fixes.

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